13th IEEE European Test Symposium

Vendor Sessions – Call for Submissions

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, practical applications, hot topics, and new trends in the area of electronic-based circuit and system testing. In 2008, ETS will take place in the nice town of Verbania, Piedmont, Lago Maggiore lakeside. ETS'08 is being organized by the Politecnico di Torino, and is sponsored by the Test Technology Technical Council (TTTC) of the IEEE Computer Society.

ETS'08 is offering commercial vendors the opportunity to give technical presentations in a track parallel to the technical paper sessions. These presentations will be listed in the symposium program along with the technical sessions, and should be targeted to the ETS technical audience. The Vendor Sessions differ from other ETS presentations in that company names, logos, and product names may be mentioned explicitly. Typical content could include product descriptions, case studies, best practices, and testimonials.

Presentation opportunities of 30-minute duration are available on a first-come first-served basis, but priority will be given to those companies that are also sponsors of ETS'08 – see below. Attendance at the sessions is open to all symposium attendees, and vendor representatives will be able to hand out literature at the session.

Review Procedure

Proposals for the Vendor Sessions should be technical or application focused rather than overtly sales-and-marketing focused. Proposal review is based on the technical content and relevance to ETS'08 audience and topics. The areas of interest of ETS'08 include (but are not limited to) the following topics:

- Analog, Mixed-Signal, RF Test
- ATE Hardware and Software
- Automatic Test Generation
- Board and System Test
- Built-In Self Test (BIST)
- Current-Based Test
- Defect and Fault Tolerance
- Delay and Performance Test
- Design for Test(ability) (DfT)
- Design Verification and Validation
- Diagnosis and Debug

- (Embedded) System Test
- Failure Analysis
- Fault Modeling and Simulation
- High-Level DfT and TPG
- High-Speed IO/Interconnect Test
- Memory Test and Repair
- MEMS and Nanotechnology Test
- Microprocessor Test
- Nanometer Technologies Test
- On-Line and Off-Line Test
- Power Issues in Test

- Self-Repair Methodologies
- Signal Integrity Test
- Standards in Testing
- System-in-Package (SiP) Test
- System-on-Chip (SoC) Test
- Test Data Compression
- Test of Reconfigurable Systems
- Test Quality and Reliability
- Test(ability) Synthesis
- Thermal Test
- Yield Analysis and Enhancement

Submissions

A submission to the ETS'08 Vendor Sessions can be an abstract, extended abstract, or full paper (max. six pages). Submission of a full paper is preferred, but not required. Proposals should be submitted via the ETS'08 web site; detailed submission instructions can also be found there (go to http://www.ieee-ets.org, follow the link to ETS'08, and then select Submission Instructions). Key dates for submissions:

- Submission deadline   : **January 25, 2008**
- Notification of acceptance : **February 17, 2008**
- Camera-ready manuscript   : **March 16, 2008**

ETS'08 Industrial Sponsorship

Every year, ETS is sponsored by several companies. The sponsorship money is used to reduce the registration fees and hence make the event more accessible to all its attendees. In return, the sponsoring companies are allowed to make publicity in various ways. ETS has defined four different sponsor grades (named Bronze, Silver, Gold, and Platinum), each with different money amounts and different publicity paths. To find out more, contact Erik Jan Marinissen, details below.

More Information

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Visit the ETS web page at: **http://www.ieee-ets.org**